



PK471 (v1.0) Jul 29, 2011

# 100% Material Declaration Data Sheet FG900 Spartan-6

**Average Weight: 4.054 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					<b>0.090946</b>	<b>2.243</b>
	Silicon	7440-21-3	100.00	Main material	0.090946	
Die Attach Material					<b>0.016016</b>	<b>0.395</b>
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
Mold Compound					<b>1.876994</b>	<b>46.302</b>
	Solid Epoxy Resin	Trade Secret	5.00	Main material	0.093850	
	Phenol Resin	Trade Secret	5.00	Main material	0.093850	
	Fused Silica	60676-86-0	87.45	Main material	1.641431	
	Metal Hydroxide	Trade Secret	2.00	Main material	0.037540	
	Carbon Black	1333-86-4	0.55	Main material	0.010323	
Gold Wire					<b>0.023056</b>	<b>0.569</b>
	Gold	7440-57-5	99.05	Main material	0.022837	
	Palladium	7440-05-3	0.95	Main material	0.000219	
Solder Balls					<b>0.856617</b>	<b>21.131</b>
	Tin (Sn)	7440-31-5	63.00	Main material	0.539669	
	Lead (Pb)	7439-92-1	37.00	Main material	0.316948	
Substrate					<b>1.190159</b>	<b>29.359</b>
	Copper	7440-50-8	28.19	Main material	0.335483	
	Nickel	7440-02-0	4.13	Main material	0.049192	
	Gold	7440-57-5	0.30	Main material	0.003529	
	BT (core)	21645-51-2 7440-50-8 Epoxy resin	59.49	Main material	0.708012	
	Solder mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6	7.89	Main material	0.093943	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/29/11	1.0	Initial Xilinx release.

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